AMENDED CLAIM SET:

1. (currently amended) A method for producing an organic thin-film device comprising the steps of

(a) heating and/or pressing a transfer material having an organic thin-film layer formed on a temporary support and a first laminate comprising a substrate and at least a transparent conductive layer or a rear-surface electrode formed on said substrate, which overlap each other such that a surface of said organic thin-film layer of said transfer material faces only the side of said substrate having said transparent conductive layer formed thereon being intended to form a receiving surface, without decompressing a space between said transfer material and said substrate, thereby forming a laminate structure;

(b) peeling said temporary support from said laminate structure to ~~non-imagewise~~ entirely transfer said organic thin-film layer to said receiving surface of said first laminate with adjusting the angle of said transfer material to said first laminate to 90° or less and a peeling angle of said temporary support from said organic thin-film layer to 90° or more; and

(c) bonding a second laminate comprising a substrate and at least a rear-surface electrode or a transparent conductive layer formed on said substrate to said organic thin-film layer ~~non-imagewise~~ entirely transferred onto said first laminate, wherein the heating is carried out by a heating means selected from the group consisting of a laminator, an infrared heater, and a roller heater.

2. (original) The method of claim 1, wherein said step (a) comprises heating and pressing.

3. (cancelled).

4. (previously presented) The method of claim 1, wherein said transfer material is formed by a wet method.

5. (previously presented) The method of claim 1, wherein said second laminate has an organic thin-film layer formed on said rear-surface electrode or said transparent conductive layer.

6. (previously presented) The method of claim 1, wherein said first laminate and said second laminate respectively have a thermal expansion coefficient of 20 ppm/°C or less.

7. (previously presented) The method of claim 1, wherein said organic thin-film layer contains at least a light-emitting, organic compound or a carrier-transporting, organic compound.

8. (previously presented) The method of claim 1, wherein a hole-transporting, organic thin-film layer, a light-emitting, organic thin-film layer and an electron-transporting, organic thin-film layer are successively transferred.

9. (previously presented) The method of claim 1, wherein at least one of said first substrate and said second substrate is provided with a transparent conductive layer.

10. (previously presented) The method of claim 1, wherein at least one of said temporary support and said substrate is in the form of a continuous web.

11. (previously presented) The method of claim 1, wherein said substrate is made of at least one material selected from the group consisting of polyimides; polyesters; polycarbonates; polyether sulfone; metal foils such as aluminum foil, copper foil, stainless steel foil, gold foil, silver foil; plastic sheets of liquid crystal polymers; fluorine-containing polymers such as poly(chlorotrifluoroethylene), polytetrafluoroethylene, polytetrafluoroethylene-polyethylene copolymers.

12. (previously presented) An organic thin-film device produced by the method of

claim 1.

13. (currently amended) A method for producing an organic electroluminescent device comprising the steps of

(a) heating and/or pressing a transfer material having an organic thin-film layer formed on a temporary support and a first laminate comprising a substrate and at least a transparent conductive layer or a rear-surface electrode formed on said substrate, which overlap each other such that a surface of said organic thin-film layer of said transfer material faces only the side of said substrate having said transparent conductive layer formed thereon being intended to form a receiving surface, without decompressing a space between said transfer material and said substrate, thereby forming a laminate structure;

(b) peeling said temporary support from said laminate structure to ~~non-imagewise~~ entirely transfer said organic thin-film layer to said receiving surface of said first laminate with adjusting the angle of said transfer material to said first laminate to 90° or less and a peeling angle of said temporary support from said organic thin-film layer to 90° or more; and

(c) bonding a second laminate comprising a substrate and at least a rear-surface electrode or a transparent conductive layer formed on said substrate to said organic thin-film layer ~~non-imagewise~~ entirely transferred onto said first laminate, wherein the heating is carried out by a heating means selected from the group consisting of a laminator, an infrared heater, and a roller heater.

14. (original) The method of claim 13, wherein said step (a) comprises heating and pressing.

15. (cancelled).

16. (previously presented) The method of claim 13, wherein said second laminate has an organic thin-film layer formed on said rear-surface electrode or said transparent conductive layer.

17. (currently amended) A method for producing an organic thin-film device comprising the steps of

(a) heating and/or pressing a transfer material having an organic thin-film layer formed on a temporary support and a first laminate comprising a substrate and at least a transparent conductive layer or a rear-surface electrode formed on said substrate, which overlap each other such that a surface of said organic thin-film layer of said transfer material faces only the side of said substrate having said transparent conductive layer formed thereon being intended to form a receiving surface, without decompressing a space between said transfer material and said substrate, thereby forming a laminate structure;

(b) peeling said temporary support from said laminate structure to ~~non-imagewise~~ entirely transfer said organic thin-film layer to said receiving surface of said first laminate with adjusting the angle of said transfer material to said first laminate to 90° or less and a peeling angle of said temporary support from said organic thin-film layer to 90° or more; and

(c) bonding a second laminate comprising a substrate and at least a rear-surface electrode or a transparent conductive layer formed on said substrate to said organic thin-film layer ~~non-imagewise~~ entirely transferred onto said first laminate, wherein the heating and/or pressing is carried out by at least one of a laminator, an infrared heater, and a roller heater.

18. (currently amended) A method for producing an organic electroluminescent device comprising the steps of

(a) heating and/or pressing a transfer material having an organic thin-film layer formed on a temporary support and a first laminate comprising a substrate and at least a transparent conductive layer or a rear-surface electrode formed on said substrate, which overlap each other such that a surface of said organic thin-film layer of said transfer material faces only the side of said substrate having said transparent conductive layer formed thereon being intended to form a receiving surface, without decompressing a space between said transfer material and said substrate, thereby forming a laminate structure;

(b) peeling said temporary support from said laminate structure to ~~non-imagewise~~

entirely transfer said organic thin-film layer to said receiving surface of said first laminate with adjusting the angle of said transfer material to said first laminate to 90° or less and a peeling angle of said temporary support from said organic thin-film layer to 90° or more; and

(c) bonding a second laminate comprising a substrate and at least a rear-surface electrode or a transparent conductive layer formed on said substrate to said organic thin-film layer ~~non-imagewise~~ entirely transferred onto said first laminate, wherein the heating and/or pressing is carried out by at least one of a laminator, an infrared heater, and a roller heater.